



QNHCHIP

QNN80N10

# Product Specification

**QNN80N10**

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100V N-Channel MOSFET



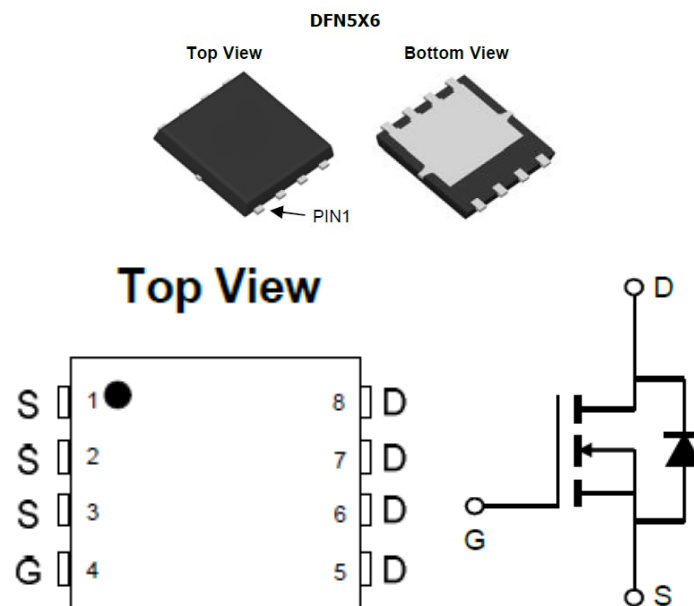
## FEATURES

- 100V,93A  
 $R_{DS(ON)}$  (@  $V_{GS} = 10V$ ) TYP= 5.6 m  $\Omega$   
 $R_{DS(ON)}$  (@  $V_{GS} = 4.5V$ ) TYP= 7.3 m  $\Omega$
- Ultra-low  $R_{DS(ON)}$
- Low Gate Charge
- Pb-free Lead Plating
- Halogen-free and RoHS-compliant

## Applications

- Power Management in Telecom., Industrial Automation, CE
- Current Switching in DC/DC & AC/DC Sub-systems
- Motor Driving in Power Tool, E-vehicle, Robotics

## Pin Description



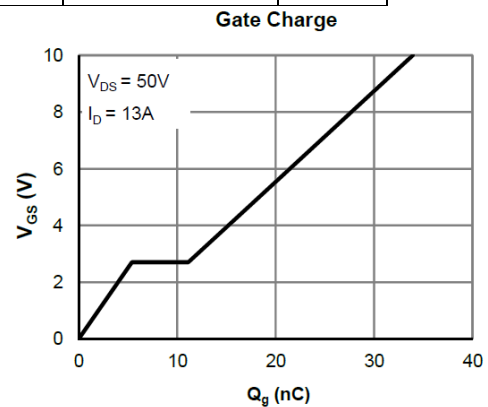
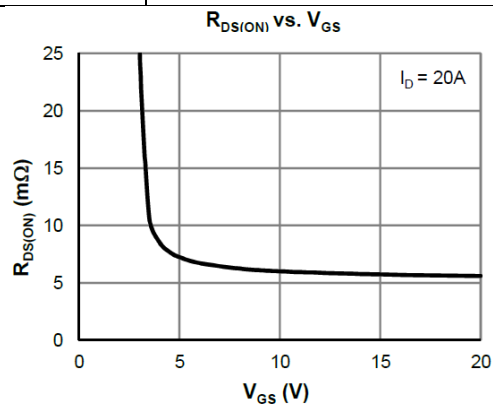
NO.	Symbol	Description
1	S	SOURCE
2	S	SOURCE
3	S	SOURCE
4	G	GATE
5	D	DRAIN
6	D	DRAIN
7	D	DRAIN
8	D	DRAIN



## Absolute Maximum Ratings

(@  $T_C = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Value	Unit	
$V_{DS}$	Drain-to-Source Voltage	100	V	
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V	
$I_D$	Continuous Drain Current <sup>(1)</sup>	$T_C = 25^\circ\text{C}$	93	A
		$T_C = 100^\circ\text{C}$	54	
$I_{DM}$	Pulsed Drain Current <sup>(2)</sup>	210	A	
$I_{AS}$	Avalanche Current <sup>(3)</sup>	45	A	
$E_{AS}$	Avalanche Energy <sup>(3)</sup>	101	mJ	
$P_D$	Power Dissipation <sup>(4)</sup>	$T_C = 25^\circ\text{C}$	104	W
		$T_C = 100^\circ\text{C}$	42	
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$	





## Electrical Characteristics

( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	100			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=80\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1.0 5.0	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.2	1.7	2.5	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$		5.6	7.4	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=15\text{A}$		7.3	10.0	$\text{m}\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=20\text{A}$		82		S
$V_{SD}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.72	1.0	V
$I_S$	Diode Continuous Current	$T_C=25^\circ\text{C}$			104	A
<b>DYNAMIC PARAMETERS <sup>(5)</sup></b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=50\text{V},$ $f=1\text{MHz}$		2200		pF
$C_{oss}$	Output Capacitance			791		pF
$C_{riss}$	Reverse Transfer Capacitance			143		pF
$R_g$	Gate Resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		1.8		$\mu\Omega$
<b>SWITCHING PARAMETERS <sup>(5)</sup></b>						
$Q_g$	Total Gate Charge (@ $V_{GS}=10\text{V}$ )	$V_{GS}=0\sim 10\text{V}$ $V_{DS}=50\text{V}, I_D=13\text{A}$		34		nC
$Q_g$	Total Gate Charge (@ $V_{GS}=4.5\text{V}$ )			17.0		nC
$Q_{gs}$	Gate Source Charge			5.5		nC
$Q_{gd}$	Gate Drain Charge			5.7		nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=50\text{V},$ $R_L=3.8\Omega, R_{GEN}=6\Omega$		13.0		ns
$t_r$	Turn-On Rise Time			14.0		ns
$t_{D(off)}$	Turn-Off DelayTime			29		ns
$t_f$	Turn-Off Fall Time			17.0		ns
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=13\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$		51		ns
$Q_{rr}$	Body Diode Reverse Recovery Charge	$I_F=13\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$		90		nC
<b>Thermal Performance</b>						
Symbol	Parameter	Typ.	Max.	Unit		
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	50	65	$^\circ\text{C}/\text{W}$		
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.0	1.2	$^\circ\text{C}/\text{W}$		

Notes:

1. Computed continuous current assumes the condition of  $T_{J\_Max}$  while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under  $T_{J\_Max}=150^\circ\text{C}$ .
3. This single-pulse measurement was taken under the following condition [ $L=100\mu\text{H}, V_{GS}=10\text{V}, V_{DS}=50\text{V}$ ] while its value is limited by  $T_{J\_Max}=150^\circ\text{C}$
4. The power dissipation PD is based on  $T_{J\_Max}=150^\circ\text{C}$ .
5. This value is guaranteed by design hence it is not included in the production test.



## Typical Electrical & Thermal Characteristics

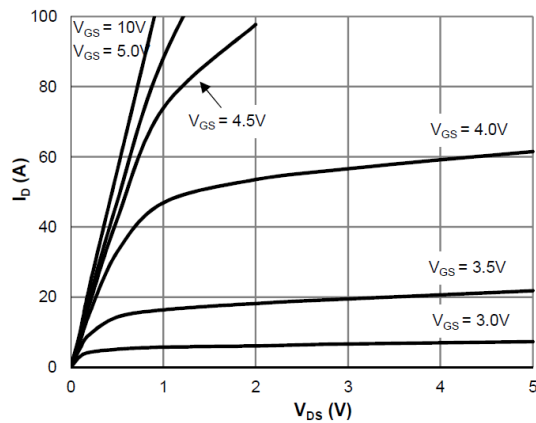


Figure 1: Saturation Characteristics

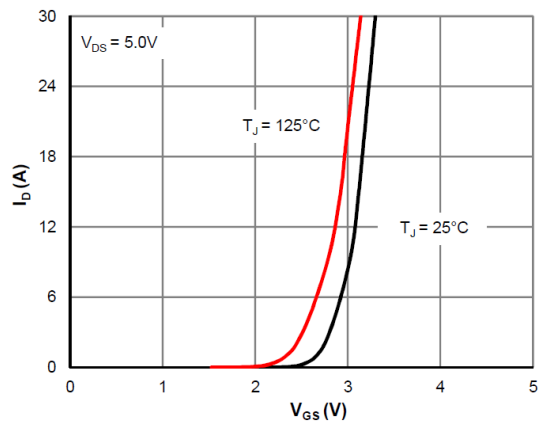


Figure 2: Transfer Characteristics

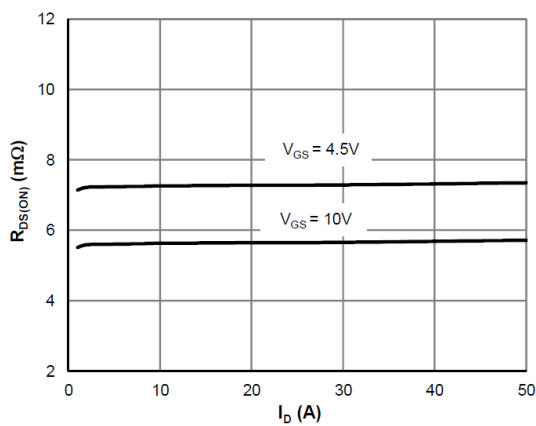


Figure 3:  $R_{DS(ON)}$  vs. Drain Current

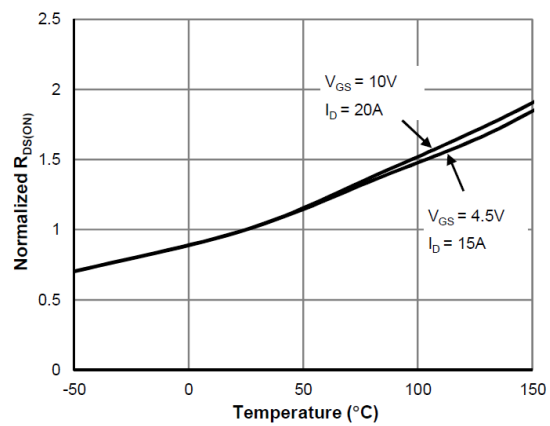


Figure 4:  $R_{DS(ON)}$  vs. Junction Temperature

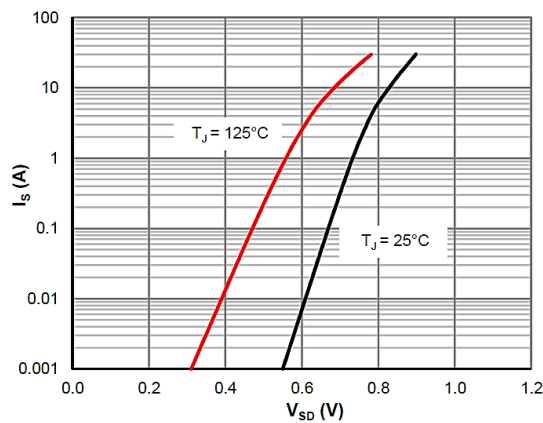


Figure 5: Body-Diode Characteristics

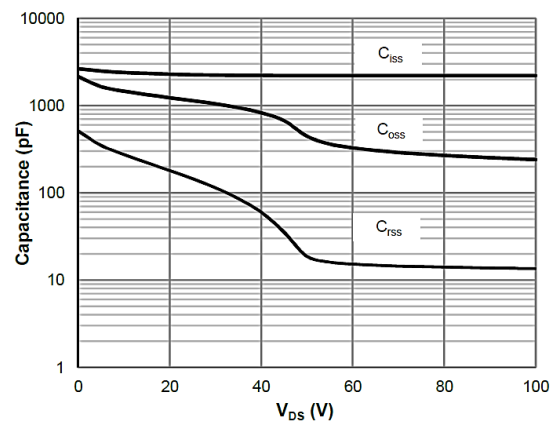


Figure 6: Capacitance Characteristics

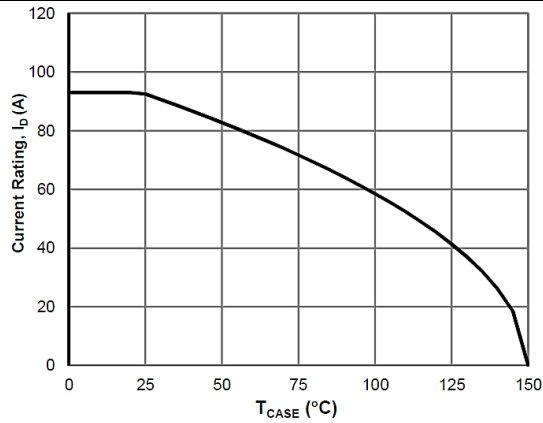


Figure 7: Current De-rating

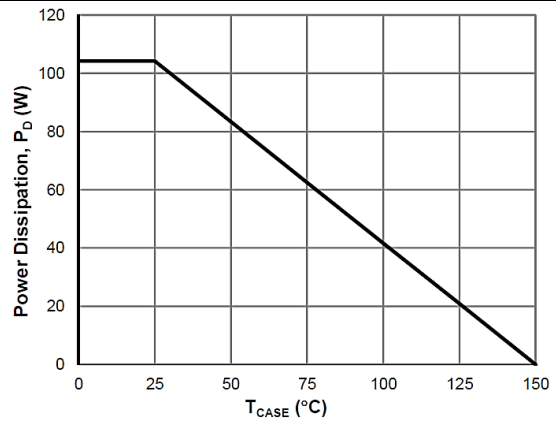


Figure 8: Power De-rating

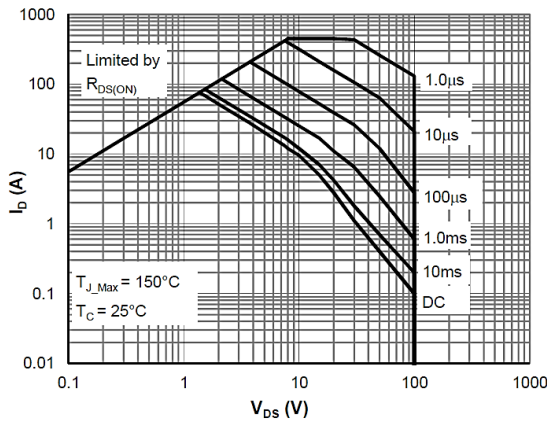


Figure 9: Maximum Safe Operating

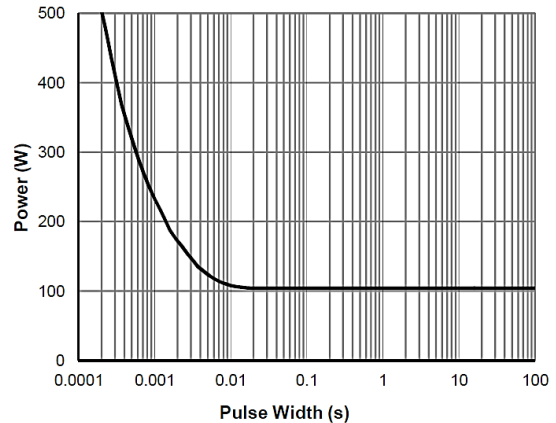


Figure 10: Single Pulse Power Rating, Junction-to-Case

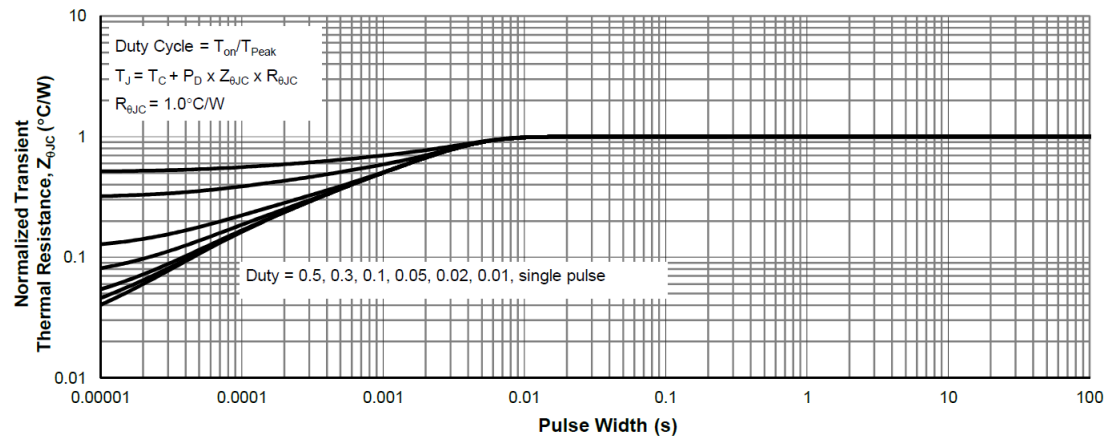
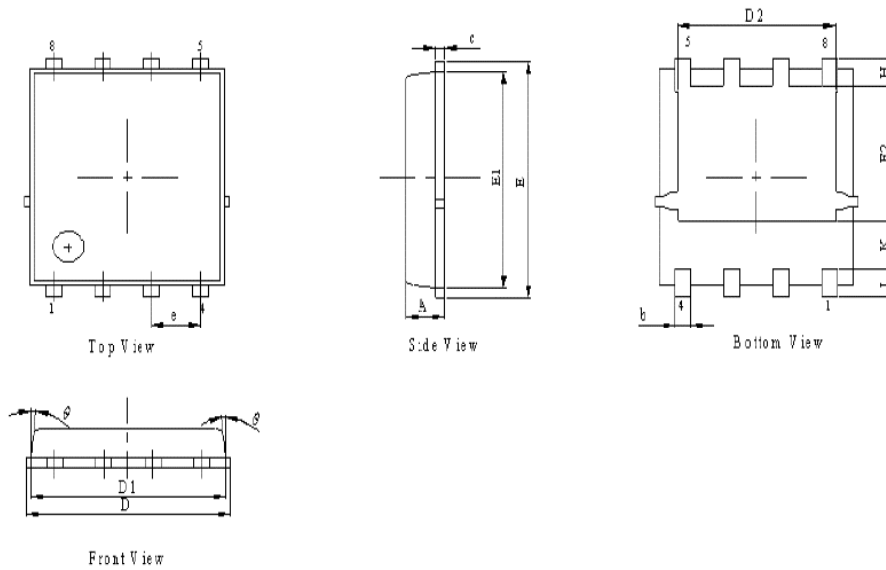


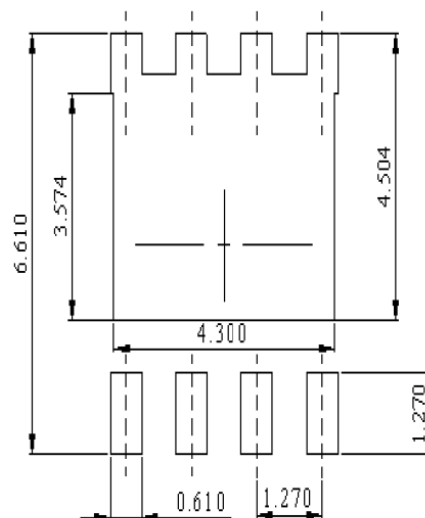
Figure 11: Normalized Maximum Transient Thermal Impedance



## Package Mechanical Data(PDFN 5x6-8L)



Symbol	Dimensions In Millimeters		
	Min.	NOM.	Max.
A	0.9	1	1.15
b	0.31	0.41	0.51
C	0.24	0.32	0.4
D	5	5.2	5.4
D1	4.95	5.05	5.15
D2	4	4.1	4.2
E	6.05	6.15	6.25
E1	5.5	5.6	5.7
E2	3.42	3.53	3.63
e	1.27 BSC		
H	0.6	0.7	0.8
L	0.5	0.7	0.8
K	1.23 BEF		
O			10



DIMENSIONS: MILLIMETERS



## Ordering information

Order Code	Package	V <sub>DS</sub> (V)	I <sub>D</sub> (A)	R <sub>DS(ON)</sub> ( m Ω )	
QNN80N10	PDFN 5x6-8	100	93	V <sub>GS</sub> =10V	5.6
				V <sub>GS</sub> =4.5V	7.3